

FEATURES

- Adaptive Conduction with TRIAC DIM.
- Wide Range, Programmable LED Voltage.
- Output LED Current available from 50mA to 100mA.
- Can be Paralleled for Higher Current
- 5V to 500V Supply Voltage Range.
- High Efficiency.
- Stable LED Brightness.
- Over Temperature Protection.
- SOP-16 Exposed Pad (150 mil) & TSSOP16 Exposed Pad Package.
- Patent Pending Drive Architecture.

APPLICATIONS

- LED Lamps (e.g. E27, GU10)
- General Illumination
- LED Strings (e.g. T-8 Tube)
- Constant Current Sink

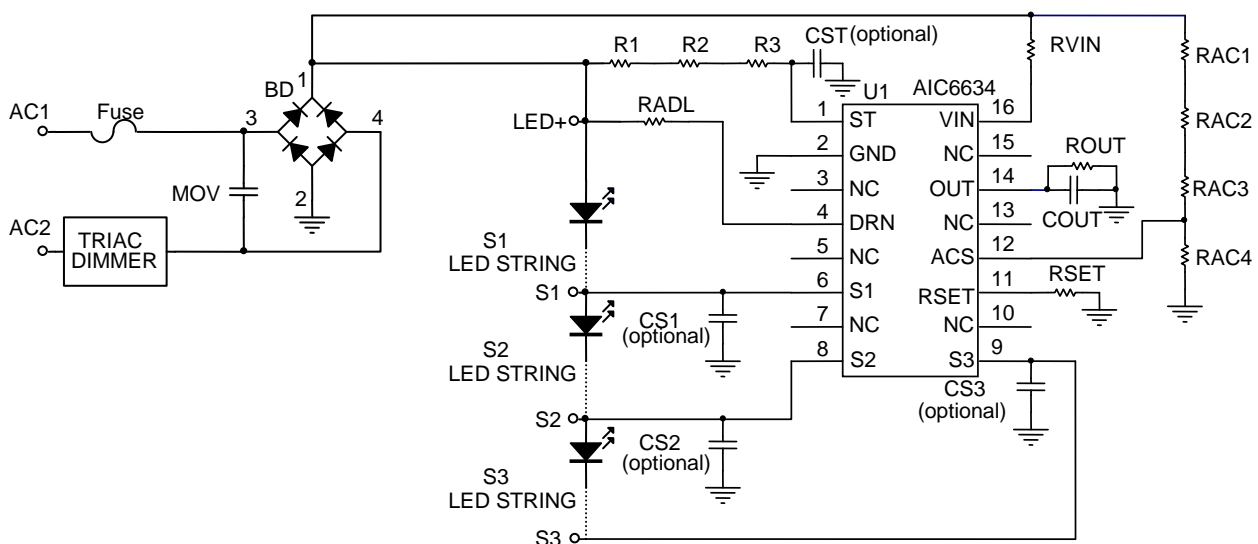
DESCRIPTION

The AIC6634 is an off-line linear LED driver. The application of high bright LED is widely used for general illumination.

The AIC6634 can drive a plurality of LED strings. When the voltage detecting circuit detects the different voltage level of input voltage, it can control the LED strings. If the input voltage is lower that it will bypass some LED strings. And turn on all LED strings when the input voltage is higher. The number of LEDs in LED array is dependent on the voltage level of the AC power source, that includes of $\pm 10\%$ variations. A typical application for the AIC6634 is to drive LEDs with a constant current of 50mA ~ 100mA. Multiple AIC6634 can also be used in parallel to provide higher currents.

The AIC6634 is available in a SOP-16 exposed pad (150 mil) & TSSOP16 exposed pad package.

TYPICAL APPLICATION CIRCUIT



Typical Application Circuit in SOP-16 Exposed Pad (150 mil) Package

ORDERING INFORMATION

AIC6634X XX XX

PACKING TYPE
TR: TAPE & REEL
TB: TUBE

PACKAGING TYPE
RE: SOP-16 Exposed Pad (150 mil)
LT: TSSOP-16 Exposed Pad

G: GREEN PACKAGE

Example: AIC6634GRETR

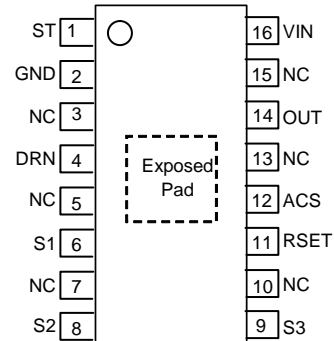
→ in Green SOP-16 Exposed Pad (150 mil) Package and Taping & Reel Packing Type

AIC6634GLTTR

→ in Green TSSOP-16 Exposed Pad Package and Taping & Reel Packing Type

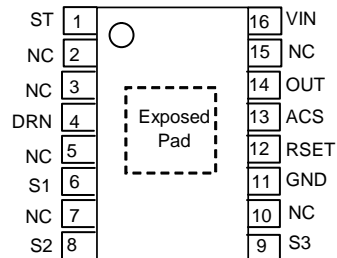
PIN CONFIGURATION

SOP-16 Exposed Pad (150 mil) TOP VIEW



Note: The exposed pad should be connected with GND pin.

TSSOP-16 Exposed Pad TOP VIEW



Note: The exposed pad should be connected with GND pin.

■ ABSOLUTE MAXIMUM RATINGS

VIN Pin Voltage	550V
S1, S2, S3, DRN Pin Voltage.....	550V
ST Pin Voltage	30V
OUT Pin Voltage	6V
RSET Pin Voltage	6V
ACS Pin Voltage	6V
Operating Ambient Temperature Range T_A	-40°C~85°C
Operating Maximum Junction Temperature T_J	150°C
Storage Temperature Range T_{STG}	-65°C~150°C
Lead Temperature (Soldering 10 Sec.).....	260°C
Thermal Resistance Junction to Case SOP-16 Exposed Pad (150 mil)*	13°C /W
Thermal Resistance Junction to Case TSSOP-16 Exposed Pad*.....	14°C /W
Thermal Resistance Junction to Ambient SOP-16 Exposed Pad (150 mil)*.....	60°C /W
Thermal Resistance Junction to Ambient TSSOP-16 Exposed Pad*... ..	50°C /W

(Assume no Ambient Airflow, no Heatsink)

Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

*The package is placed on a two layers PCB with 2 ounces copper and 2 square inch, connected by 8 vias.

■ ELECTRICAL CHARACTERISTICS

(T_J=25°C, unless otherwise specified) (Note 1)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply Voltage Section						
V _{IN} Operation Voltage		V _{IN}	5		500	V
Quiescent Current	V _{IN} =310V	I _{VIN}		350		μA
S1, S2, S3 Driver Section						
Driver Leakage Current	V _{IN} =V _{S1} =V _{S2} =230V V _{S3} =20V	I _{LK}	0		2	mA
Output LED Current (Note 2)						
LED Current Range	I _{S1} , I _{S2} , I _{S3}		50		100	mA
LED Current Tolerance	I _{S3}		-5		+5	%
Output Voltage Regulator Section						
Regulation Voltage	V _{IN} =230V I _{OUT} =0mA	V _{OUT}	4.5	5	5.5	V
Voltage Tolerance			-10		+10	%
Setting LED Current Section						
RSET Voltage	RSET=37.5KΩ	V _{RSET}		0.5		V
RSET Short	RSET=0 Ω	I _{S3}	110			mA
RSET Open	RSET=∞ Ω		0		1	mA
AC Sense Section						
ACS Voltage	R _{ACSU} =10MΩ	V _{ACS}		0.5		V
ACS Voltage Tolerance			-10		+10	%
ACS Disable Voltage	ACS connect to out pin		4.5	5	5.5	V
Over Temperature Protection						
Action Junction Temperature				140		℃

Note 1: Specifications are production tested at T_A=25°C. Specifications over the -40°C to 85°C operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).

Note 2: Output LED Current = peak to peak.

TYPICAL PERFORMANCE CHARACTERISTICS

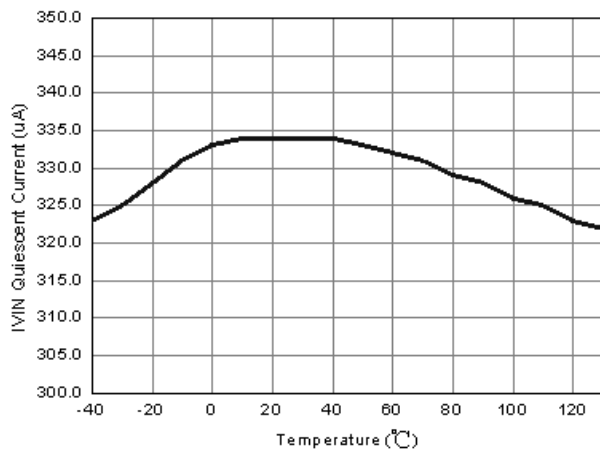


Fig.1 Quiescent Current

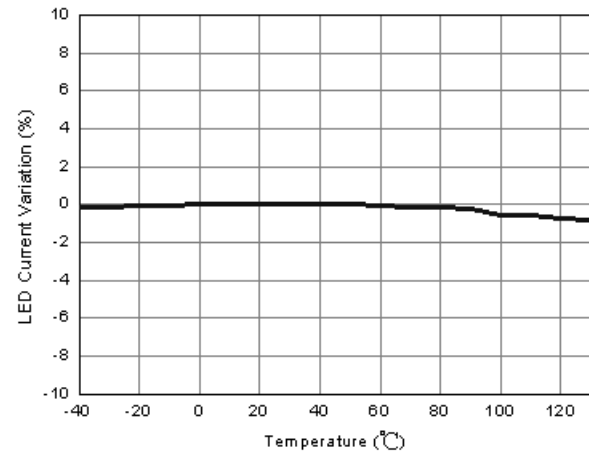


Fig.2 LED current vs. Temperature

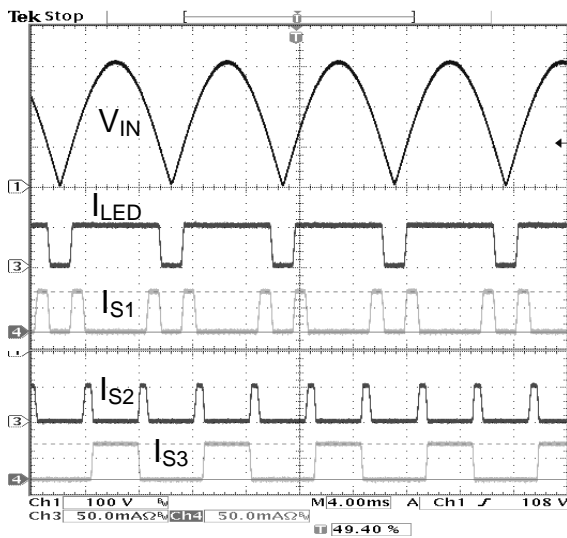


Fig.3 LED current waveform

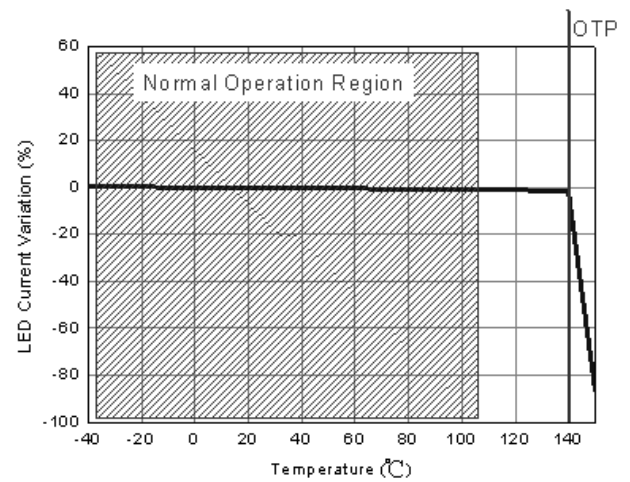


Fig.4 Over Temperature Protection

The block diagram illustrates the system architecture with the following components and connections:

- Input Pins:** VIN, ST, RSET, DRN, and GND.
- Functional Blocks:**
 - Voltage Regulator:** Receives VIN and provides power to the Current Limit block and the Bandgap block.
 - Current Limit:** Receives input from the Voltage Regulator and provides output to the OUT pin and the ACS block.
 - Startup:** Receives ST and provides input to the Voltage Regulator.
 - Bandgap:** Receives input from the Voltage Regulator and provides output to the BIAS block.
 - BIAS:** Receives input from the Bandgap and provides output to the RSET block.
 - RSET:** Receives input from the BIAS and provides output to the Current Process block.
 - ACS (Analog-to-Digital Converter):** Receives input from the Current Limit block and provides output to the OUT pin and the Current Process block.
 - Current Process:** Receives input from the RSET block and provides output to the OUT pin and the ACS block.
 - Over Temperature Protection:** Provides input to the Current Process block.
- Output Pins:** OUT, ACS, S1, S2, and S3.
- Internal Components:**
 - A 25V Zener diode connected to ST and GND.
 - A current source connected to RSET and GND.
 - Three MOSFETs connected to DRN, S1, S2, and S3, with their gates controlled by the Current Process block.

ST PIN	-Provide the Startup Current for the Controller.
VIN PIN	-Power Supply Input.
S1PIN	-LED S1 Cathode Connection.
S2PIN	-LED S2 Cathode Connection.
S3 PIN	-LED S3 Cathode Connection.
DRN PIN	-Dummy Load Controller.
OUT PIN	-Connecting an Output Capacitor to Provide a Stable Voltage for the Internal Circuit.
GND PIN	-Ground.
ACS PIN	-LED turn-on voltage. This pin does not allow floating.
RSET PIN	-Set output peak current.

■ APPLICATION INFORMATION

The AIC6634 is off-line constant current LED driver. It can drive a plurality of LED strings. The AIC6634 can flexibly control the LED strings according to the variance of input voltage. If the input voltage is lower, it will bypass some LED strings. When the input voltage is higher than the total forward voltage of all LED strings, all LED strings will be turned on. The number of LEDs in LED array is dependent on the voltage level of the AC power source. Multiple AIC6634 can also be used in parallel to provide higher LED current.

SOFT START

The AIC6634 has soft start function to reduce the inrush current during the start-up period. According to the different AC input voltage, the Table 01 provides the commanded component value for soft start resistor R_{ST} ($R_1 \sim R_3$).

Table 01

Input Voltage	Estimated R_{ST} Resistor Value
AC110V	12.2M Ω
AC120V	13.7M Ω
AC220V	25.1M Ω
AC240V	27.5M Ω

DUMMY LOAD CONTROLLER

In order to achieve stable light output when the TRIAC dimmer is used, AIC6634 designs the dummy load control function. By using a suitable dummy load R_{ADL} , the stability of light output can be improved when using the TRIAC dimmer. However, the electrical characteristics of all kinds of TRIAC dimmer are not the same. When the different TRIAC dimmer is used, the suitable dummy load may be different. In order to achieve more stable light output, the dummy load should be adjusted in accordance with the used TRIAC dimmer.

OUTPUT CAPACITOR, INPUT RESISTOR & OUTPUT RESISTOR

By connecting an output capacitor to the OUT pin and an input resistor to the VIN pin, a stable

voltage can be provided for the internal circuit of AIC6634. A 1uF~10uF output ceramic capacitor is commanded for most AIC6634 applications. When choosing the output ceramic capacitor, X5R and X7R types are recommended because they retain their capacitance over wider ranges of voltage and temperature than other types. In addition, the input resistance of R_{VIN} must be larger than 33K Ω . When choosing the SMD input resistor, the SMD input resistor size must be bigger than 0805 size.

When using the TRIAC dimmer, the stability of light output can be improved by using a suitable output resistor, R_{OUT} , in parallel with output capacitor. However, when the different TRIAC dimmer or LED string is used, the suitable output resistor may be different. In order to achieve more stable light output, the output resistor should be adjusted in accordance with the used TRIAC dimmer or LED string.

SETTING OUTPUT LED PEAK CURRENT

The output LED peak current of AIC6634 can be set by the external resistor R_{SET} . The relationship between $I_{OUT-PEAK}$ and R_{SET} is

$$R_{SET} = 3150 / I_{OUT-PEAK}$$

Turn ON/OFF LED Current

The device can be activated when the voltage at ACS pin is higher than 0.5V. It can turn off LED current when the voltage at ASC pin is lower than 0.5V. Therefore, by connecting the resistive divider R_{ACSU} ($R_{AC1} \sim R_{AC3}$) and R_{ACSD} (R_{AC4}) between the ACS pin and LED+ terminal, the device activated voltage can be set.

$$V_{LED+(ON)} = 0.5 \times \left(1 + \frac{R_{ACSU}}{R_{ACSD}} \right)$$

The recommended R_{ACSU} is 10M Ω . In additional, the ACS function can be disabled while connecting the ACS pin to OUT pin.

THERMAL REGULATION

The AIC6634 includes the thermal-regulation circuit, which is designed to protect the device

from excessive temperature. The internal thermal-regulation circuit adjusts the LED current if the junction temperature rises above the preset value of about 140°C.

POWER DISSIPATION

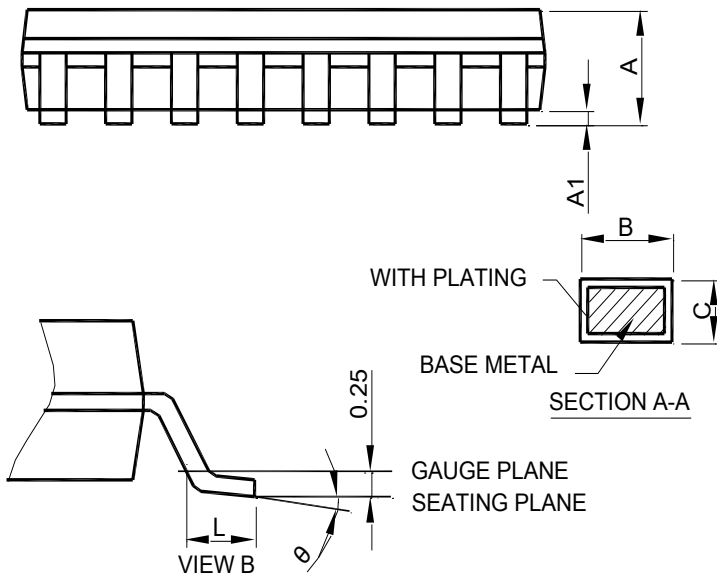
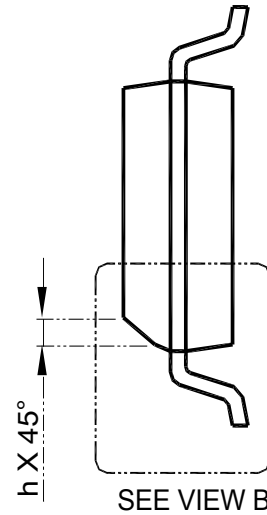
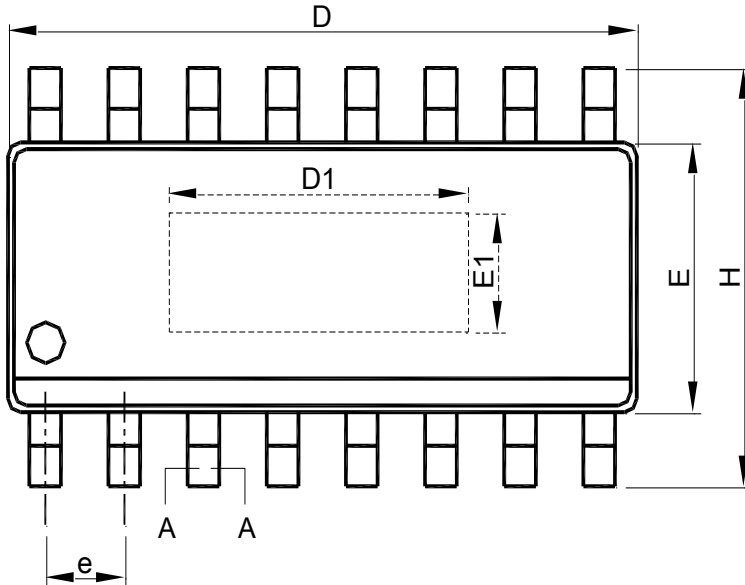
The maximum power dissipation of AIC6634 depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is

greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature.

■ PHYSICAL DIMENSIONS

● SOP-16 Exposed Pad (150 mil)



SYMBOL	SOP-16 Exposed Pad(150mil)	
	MILLIMETERS	
	MIN.	MAX.
A	1.35	1.70
A1	0.00	0.15
B	0.31	0.51
C	0.10	0.25
D	9.80	10.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
θ	0°	8°
D1	3.30	5.00
E1	1.30	2.80

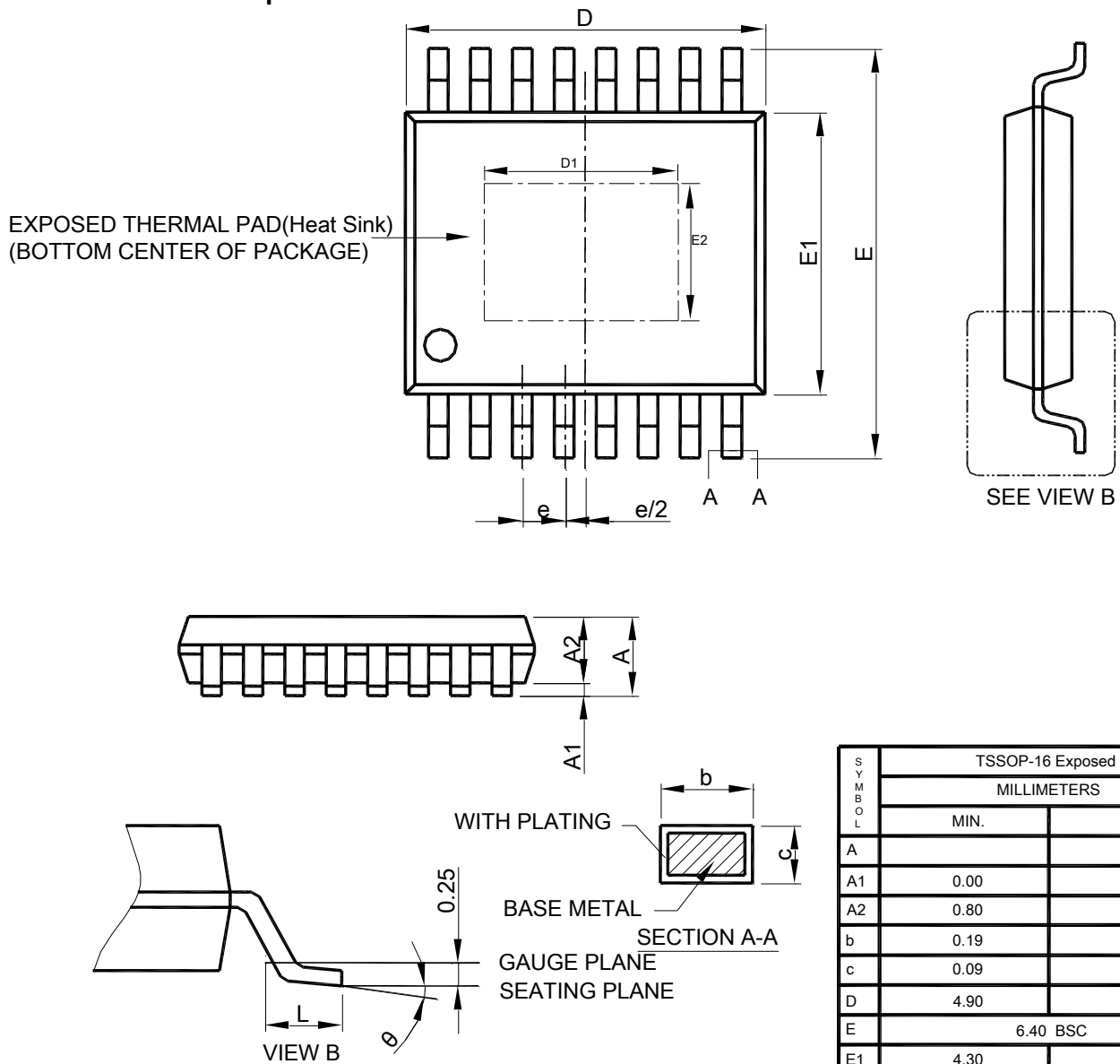
Note: 1. Refer to JEDEC MS-012AC.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side on.

3. Dimension "E" does not include inter-lead flash or protrusions.

4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

● TSSOP-16 Exposed Pad



- Note: 1. Refer to JEDEC MO-153AB.
 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
 3. Dimension "E1" does not include inter-lead flash or protrusions.
 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

SYMBOL	TSSOP-16 Exposed Pad	
	MILLIMETERS	
	MIN.	MAX.
A		1.20
A1	0.00	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	4.90	5.10
E	6.40 BSC	
E1	4.30	4.50
e	0.65 BSC	
L	0.45	0.75
θ	0°	8°
D1	2.00	4.00
E2	1.80	3.40

Note:

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